

3.0x2.0mm SURFACE MOUNT LED LAMP

Part Number: AA3021SGS Super Bright Green

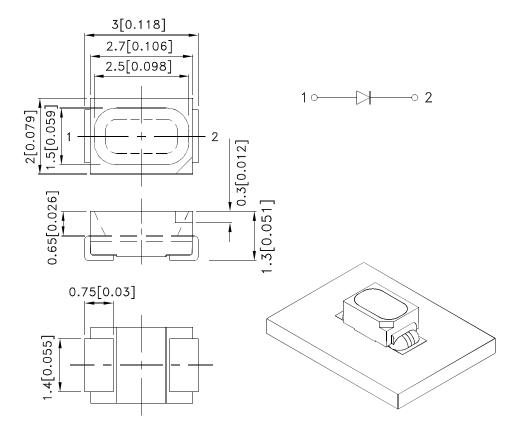
Features

- 3.0mm x 2.0mm, 1.3mm high, only minimum space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



SPEC NO: DSAL0109

APPROVED: WYNEC

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

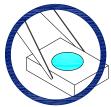
REV NO: V.1 DATE: JUL/30/2010 PAGE: 1 OF 6 **CHECKED: Allen Liu** DRAWN: F.F.Zhou ERP: 1201006489

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

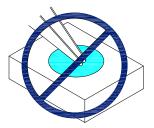
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

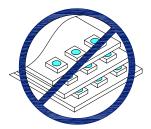


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

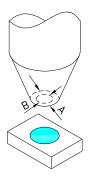




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



SPEC NO: DSAL0109 REV NO: V.1 DATE: JUL/30/2010 PAGE: 2 OF 6

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: F.F.Zhou ERP: 1201006489

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AA3021SGS	Super Bright Green (GaP)	WATER CLEAR	10	22	125°

- Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA	
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	IF=20mA	
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA	
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	IF=20mA	
lr	Reverse Current	Super Bright Green		10	uA	V _R =5V	

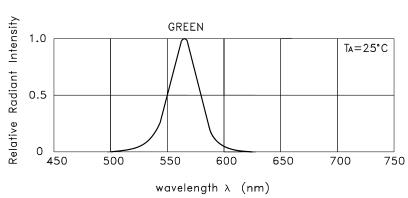
- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

A SOCIALO MAXIMAM NAMED AT 17. 20 C					
Parameter	Super Bright Green	Units			
Power dissipation	62.5	mW			
DC Forward Current	25	mA			
Peak Forward Current [1]	140	mA			
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

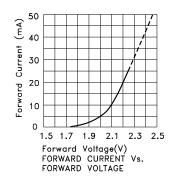
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

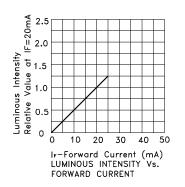
SPEC NO: DSAL0109 **REV NO: V.1** DATE: JUL/30/2010 PAGE: 3 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: F.F.Zhou ERP: 1201006489

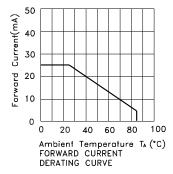


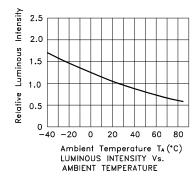
RELATIVE INTENSITY Vs. WAVELENGTH

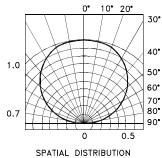
Super Bright Green AA3021SGS









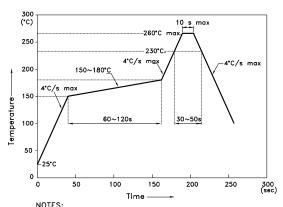


SPEC NO: DSAL0109 **REV NO: V.1** DATE: JUL/30/2010 PAGE: 4 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: F.F.Zhou ERP: 1201006489

AA3021SGS

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



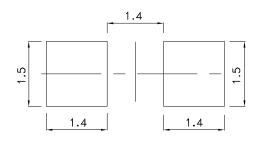
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

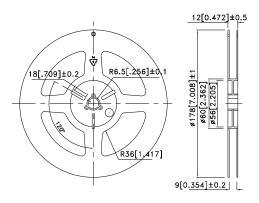
 3.Number of reflow process shall be 2 times or less.

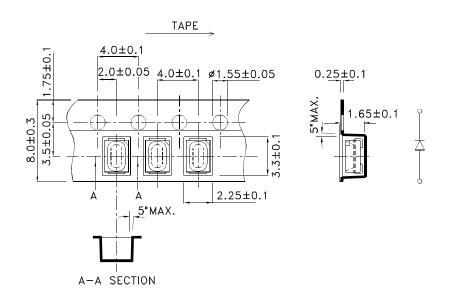
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)

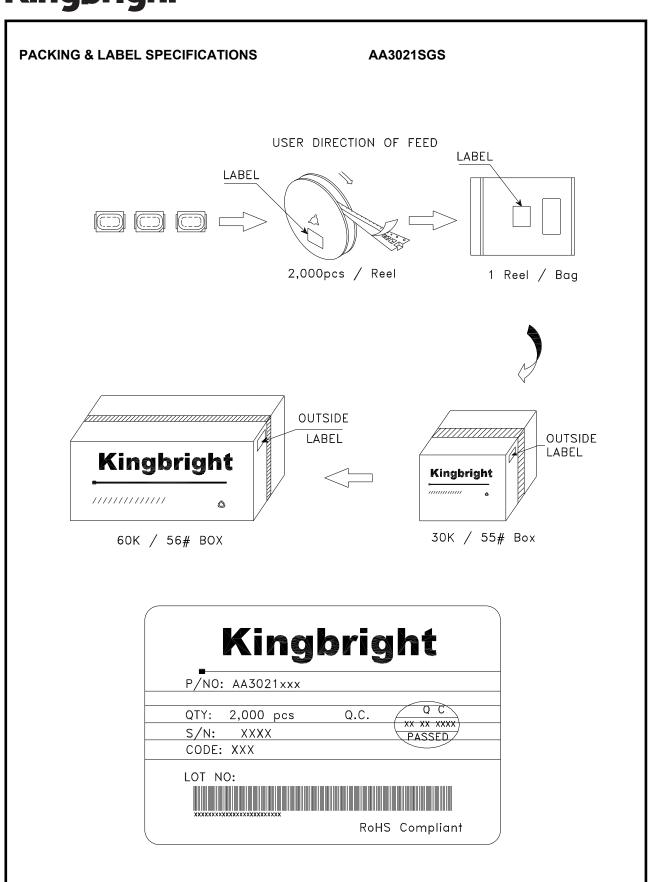
Reel Dimension





SPEC NO: DSAL0109 REV NO: V.1 DATE: JUL/30/2010 PAGE: 5 OF 6

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: F.F.Zhou ERP: 1201006489



SPEC NO: DSAL0109
APPROVED: WYNEC

REV NO: V.1 CHECKED: Allen Liu DATE: JUL/30/2010 DRAWN: F.F.Zhou PAGE: 6 OF 6 ERP: 1201006489